

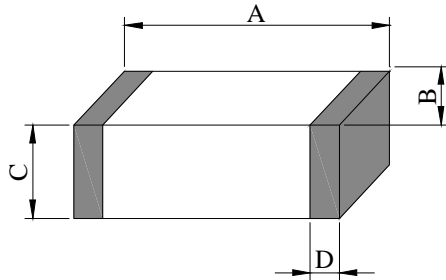
SPECIFICATION FOR APPROVAL

REF : 20100428-B

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PROD. NAME	MULTILAYER CHIP INDUCTOR	ABC'S DWG NO.	MH1608□□□□L□-□□□
		ABC'S ITEM NO.	

I . CONFIGURATION & DIMENSIONS :



- A : 1.60±0.15 m/m
- B : 0.80±0.15 m/m
- C : 0.80±0.15 m/m
- D : 0.30±0.20 m/m

II . SCHEMATIC DIAGRAM :



III . FEATURES :

- a . Monolithic structure ensuring high performance and reliability.
- b . High frequency applications up to 6GHz.
- c . Terminal : Ag/Cu/Ni/Sn
- d . Remark : Products comply with RoHS' requirements

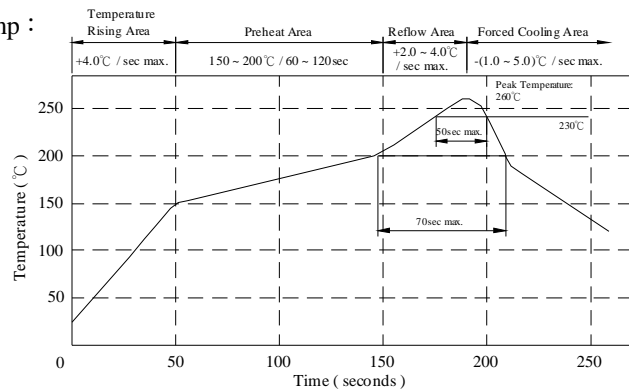
IV . APPLICATIONS :

- a . RF modules for telecommunication systems including GSM, PCS,DECT,WLAN,Bluetooth,etc.

V . GENERAL SPECIFICATION :

- a . Storage Conditions :
Electrical Performance temp : -55°C ~ +125°C
Terminal Solderability & Packages Material temp : -10°C ~ +40°C and RH 70% max.
- b . Operating temp. : -55°C ---- +125°C
- c . Solderability : Preheat : 150±25°C for 60 seconds
Solder : Sn96.5 / Ag3 / Cu0.5 or equivalent
Solder temp. : 260±5°C
Flux : Rosin
Dip time : 4±1 seconds

Peak Temp : 260°C max.
Max time above 230°C : 50sec max.
Max time above 200°C : 70sec max.



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VI . ELECTRICAL CHARACTERISITCS :

DWG No.	Inductance (nH)	Q min.	L / Q Test Freq. (MHz)	SRF (MHz) typ.	RDC (Ω) max.	IDC (mA) max.
MH16081N0DL□-□□□	1.0 ± 0.3	8	100	10000	0.10	600
MH16081N2DL□-□□□	1.2 ± 0.3	8	100	10000	0.10	600
MH16081N5DL□-□□□	1.5 ± 0.3	8	100	8000	0.10	600
MH16081N8DL□-□□□	1.8 ± 0.3	8	100	8000	0.10	600
MH16082N2DL□-□□□	2.2 ± 0.3	8	100	7200	0.10	600
MH16082N7DL□-□□□	2.7 ± 0.3	10	100	6200	0.10	600
MH16083N3DL□-□□□	3.3 ± 0.3	10	100	5200	0.12	600
MH16083N9DL□-□□□	3.9 ± 0.3	10	100	5000	0.14	600
MH16084N3DL□-□□□	4.3 ± 0.3	10	100	4750	0.16	600
MH16084N7DL□-□□□	4.7 ± 0.3	10	100	4750	0.16	600
MH16085N6DL□-□□□	5.6 ± 0.3	10	100	4100	0.18	600
MH16086N8JL□-□□□	6.8 ± 5%	10	100	3750	0.22	600
MH16087N5JL□-□□□	7.5 ± 5%	10	100	3300	0.24	600
MH16088N2JL□-□□□	8.2 ± 5%	10	100	3300	0.24	600
MH160810NJL□-□□□	10.0 ± 5%	12	100	3000	0.26	600
MH160812NJL□-□□□	12.0 ± 5%	12	100	2600	0.28	600
MH160815NJL□-□□□	15.0 ± 5%	12	100	2500	0.32	600
MH160818NJL□-□□□	18.0 ± 5%	12	100	2400	0.35	600
MH160822NJL□-□□□	22.0 ± 5%	12	100	2000	0.40	500
MH160827NJL□-□□□	27.0 ± 5%	12	100	1900	0.45	500
MH160833NJL□-□□□	33.0 ± 5%	12	100	1600	0.55	400
MH160839NJL□-□□□	39.0 ± 5%	12	100	1400	0.60	400
MH160847NJL□-□□□	47.0 ± 5%	12	100	1300	0.70	400
MH160856NJL□-□□□	56.0 ± 5%	12	100	1100	0.75	400
MH160862NJL□-□□□	62.0 ± 5%	12	100	1050	0.85	400
MH160868NJL□-□□□	68.0 ± 5%	12	100	1050	0.85	400
MH160882NJL□-□□□	82.0 ± 5%	12	100	900	1.00	300
MH1608R10JL□-□□□	100.0 ± 5%	12	100	770	1.20	300
MH1608R12JL□-□□□	120.0 ± 5%	8	50	850	2.30	300
MH1608R15JL□-□□□	150.0 ± 5%	8	50	550	2.40	250
MH1608R18JL□-□□□	180.0 ± 5%	8	50	520	2.70	250
MH1608R22JL□-□□□	220.0 ± 5%	8	50	500	3.00	250

1). □ : Packaging Information... **A** : Bulk **B** : Taping Reel

2). "- □□□" : Reference code

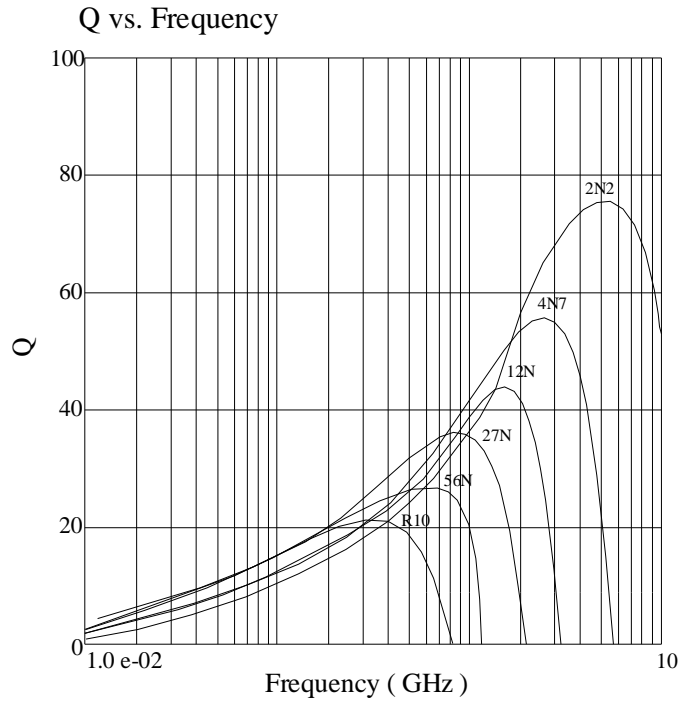
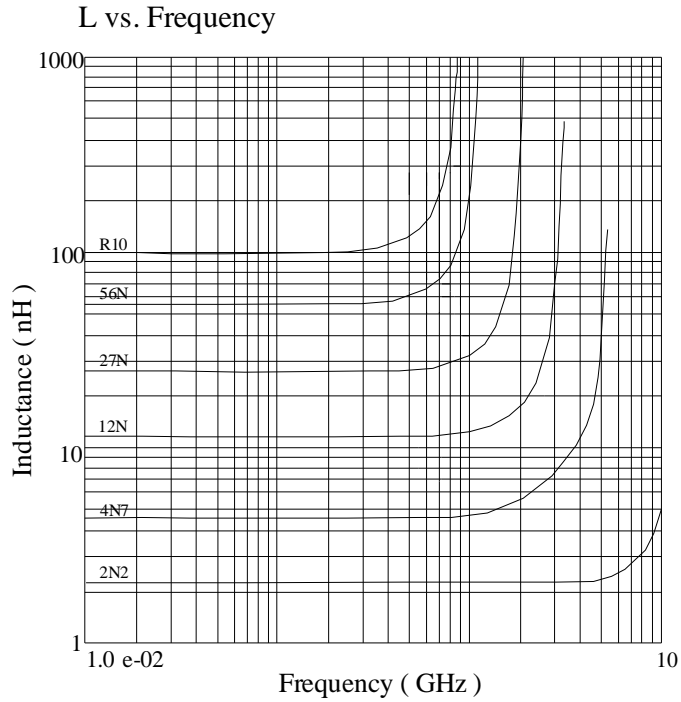
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VII . L / Q VS. FREQ. CURVE :



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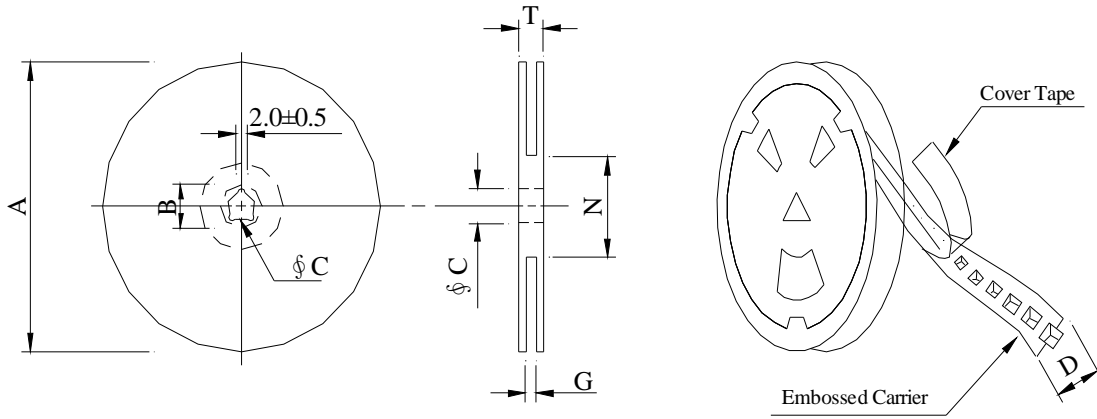
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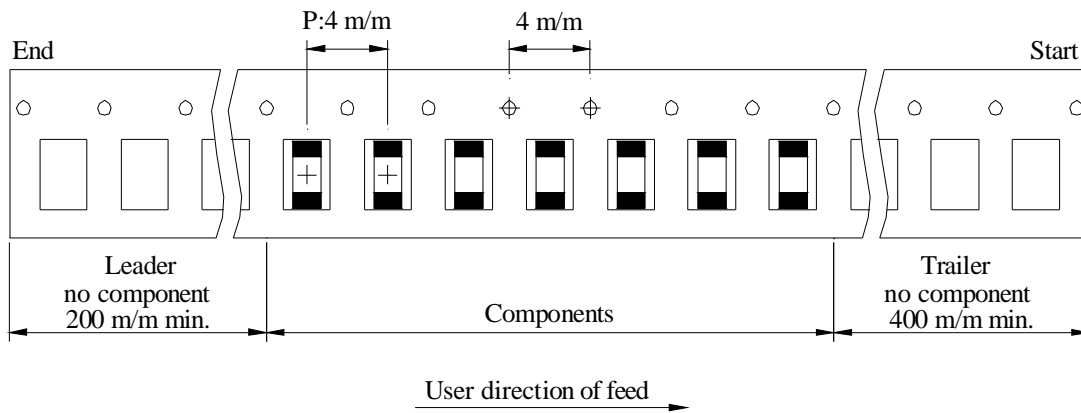
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VIII . PACKAGING INFORMATION :

(1) Configuration



※Carrier tape width : D



(2) Dimensions

Unit:m/m

Style	A	B	C	D	G	N	T
07 - 08	178	21±0.8	13	8	10 ⁺⁰	50 ⁻⁰	12.5

(3) Q'TY & G.W. Per package

Series	Inner : Reel			Outer : Carton		
	Q'TY (pcs)	G.W. (gw)	Style	Q'TY (pcs)	G.W. (Kg)	Size (cm)
MH1608	4,000	90	07 - 08	200,000	7.0	41 x 39 x 22

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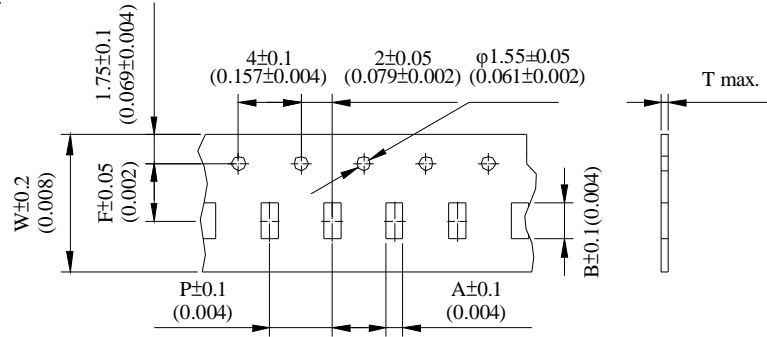
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(4) TYPE DIMENSIONS

Fig 1.



Unit:m/m

Type	A	B	F	P	T	W	Fig
MH1608	1.05	1.85	3.50	4.0	1.10	8.0	1

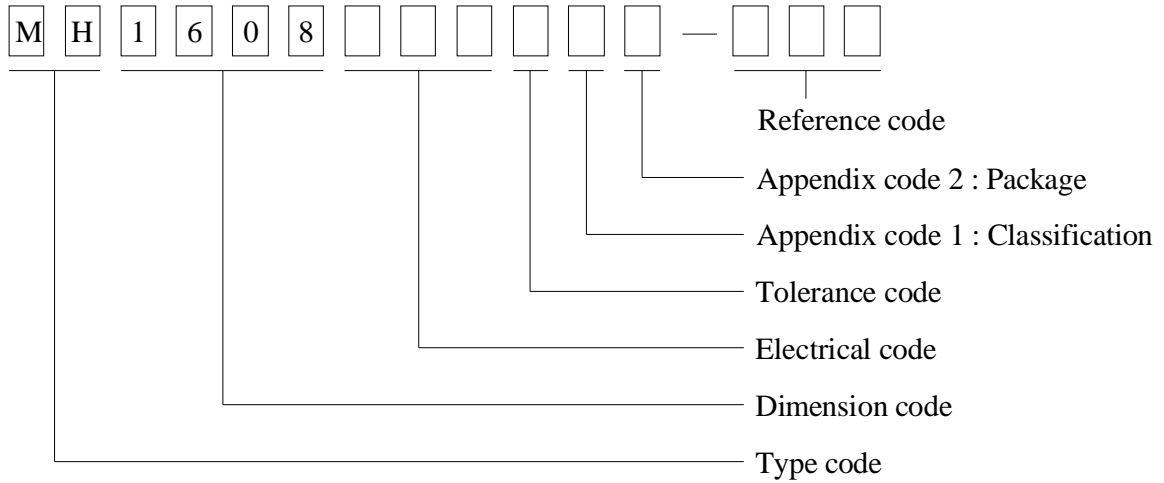
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IX . DWGING NUMBER EXPRESSION :



Appendix code 1 : Product Classification

- L : Lead Free Standard products comply with RoHS' requirements
- 1 ~ 9 : Lead Free Special products comply with RoHS' requirements

Appendix code 2 : Package Information

Code	Inner package	Inner package Q'TY	Remark
A	T.B.D.	T.B.D.	
B	T / R (Reel package)	4000 pcs	